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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	Z8S180
Number of Cores/Bus Width	1 Core, 8-Bit
Speed	33MHz
Co-Processors/DSP	-
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8s18033vsc

GENERAL DESCRIPTION (Continued)

Power connections follow the conventional descriptions below:

Connection	Circuit	Device
Power	V_{CC}	V_{DD}
Ground	GND	V_{SS}

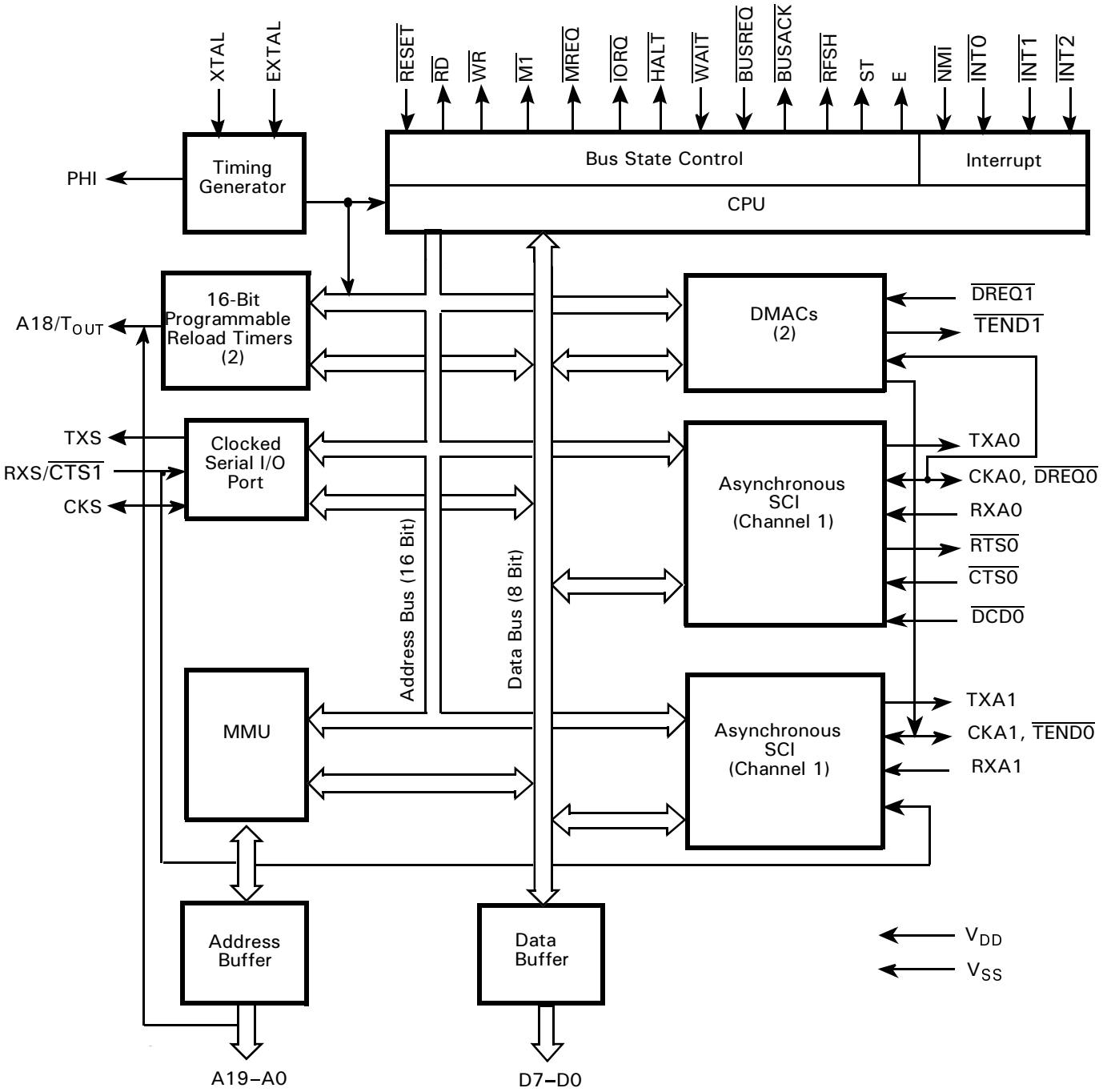


Figure 1. Z8S180/Z8L180 Functional Block Diagram

PIN IDENTIFICATION (Continued)

Table 2. Pin Status During RESET, BUSACK, and SLEEP Modes

Pin Number and Package Type					Pin Status		
QFP	PLCC	DIP	Default Function	Secondary Function	RESET	BUSACK	SLEEP
1	9	8	$\overline{NMI}$		IN	IN	IN
2			NC				
3			NC				
4	10	9	$\overline{INT0}$		IN	IN	IN
5	11	10	$\overline{INT1}$		IN	IN	IN
6	12	11	$\overline{INT2}$		IN	IN	IN
7	13	12	ST		High	High	High
8	14	13	A0		3T	3T	High
9	15	14	A1		3T	3T	High
10	16	15	A2		3T	3T	High
11	17	16	A3		3T	3T	High
12	18		V_{SS}		V_{SS}	V_{SS}	V_{SS}
13	19	17	A4		3T	3T	High
14			NC				
15	20	18	A5		3T	3T	High
16	21	19	A6		3T	3T	High
17	22	20	A7		3T	3T	High
18	23	21	A8		3T	3T	High
19	24	22	A9		3T	3T	High
20	25	23	A10		3T	3T	High
21	26	24	A11		3T	3T	High
22			NC				
23			NC				
24	27	25	A12		3T	3T	High
25	28	26	A13		3T	3T	High
26	29	27	A14		3T	3T	High
27	30	28	A15		3T	3T	High
28	31	29	A16		3T	3T	High
29	32	30	A17		3T	3T	High
30			NC				
31	33	31	A18		3T	3T	High
			T_{OUT}		N/A	OUT	OUT
32	34	32	V_{DD}		V_{DD}	V_{DD}	V_{DD}
33	35		A19		3T	3T	High
34	36	33	V_{SS}		V_{SS}	V_{SS}	V_{SS}
35	37	34	D0		3T	3T	3T
36	38	35	D1		3T	3T	3T
37	39	36	D2		3T	3T	3T
38	40	37	D3		3T	3T	3T

Table 2. Pin Status During RESET, BUSACK, and SLEEP Modes (Continued)

Pin Number and Package Type					Pin Status		
QFP	PLCC	DIP	Default Function	Secondary Function	RESET	BUSACK	SLEEP
39	41	38	D4		3T	3T	3T
40	42	39	D5		3T	3T	3T
41	43	40	D6		3T	3T	3T
42			NC				
43			NC				
44	44	41	D7		3T	3T	3T
45	45	42	$\overline{RTS0}$		High	OUT	High
46	46	43	$\overline{CTS0}$		IN	OUT	IN
47	47	44	$\overline{DCD0}$		IN	IN	IN
48	48	45	TXA0		High	OUT	OUT
49	49	46	RXA0		IN	IN	IN
50	50	47	CKA0		3T	I/O	I/O
			$\overline{DREQ0}$		N/A	IN	IN
51			NC				
52	51	48	TXA1		High	OUT	OUT
53	52		TEST				
54	53	49	RXA1		IN	IN	IN
55	54	50	CKA1		3T	I/O	I/O
			$\overline{TEND0}$		N/A	High	High
56	55	51	TXS		High	OUT	OUT
57	56	52	RXS		IN	IN	IN
			$\overline{CTS1}$		N/A	IN	IN
58	57	53	CKS		3T	I/O	I/O
59	58	54	$\overline{DREQ1}$		IN	3T	IN
60	59	55	$\overline{TEND1}$		High	OUT	High
61	60	56	$\overline{HALT}$		High	High	Low
62			NC				
63			NC				
64	61	57	$\overline{RFSH}$		High	OUT	High
65	62	58	$\overline{IORQ}$		High	3T	High
66	63	59	$\overline{MREQ}$		High	3T	High
67	64	60	E		Low	OUT	OUT
68	65	61	$\overline{M1}$		High	High	High
69	66	62	$\overline{WR}$		High	3T	High
70	67	63	$\overline{RD}$		High	3T	High
71	68	64	PHI		OUT	OUT	OUT
72	1	1	V_{SS}		GND	GND	GND
73	2		V_{SS}		GND	GND	GND
74	3	2	XTAL		OUT	OUT	OUT
75			NC				

PIN DESCRIPTIONS (Continued)

ways recognized at the end of an instruction, regardless of the state of the interrupt-enable flip-flops. This signal forces CPU execution to continue at location 0066H.

PHI. System Clock (Output). The output is used as a reference clock for the MPU and the external system. The frequency of this output may be one-half, equal to, or twice the crystal or input clock frequency.

$\overline{RD}$. Read (Output, active Low, 3-state). $\overline{RD}$ indicates that the CPU wants to read data from either memory or an I/O device. The addressed I/O or memory device should use this signal to gate data onto the CPU data bus.

$\overline{RFSH}$. Refresh (Output, active Low). Together with $\overline{MREQ}$, $\overline{RFSH}$ indicates that the current CPU machine cycle and the contents of the address bus should be used for refresh of dynamic memories. The low-order 8 bits of the address bus (A7–A0) contain the refresh address. *This signal is analogous to the $\overline{REF}$ signal of the Z64180.*

$\overline{RTS0}$. Request to Send 0 (Output, active Low); a programmable MODEM control signal for ASCI channel 0.

RXA0, RXA1. Receive Data 0 and 1 (Input). These signals are the receive data for the ASCI channels.

RXS. Clocked Serial Receive Data (Input). This line is the receive data for the CSI/O channel. RXS is multiplexed with the $\overline{CTS1}$ signal for ASCI channel 1.

ST. Status (Output). This signal is used with the $\overline{M1}$ and $\overline{HALT}$ output to decode the status of the CPU machine cycle. See Table 3.

Table 3. Status Summary

ST	$\overline{HALT}$	$\overline{M1}$	Operation
0	1	0	CPU Operation (1st Opcode Fetch)
1	1	0	CPU Operation (2nd Opcode and 3rd Opcode Fetch)
1	1	1	CPU Operation (MC Except Opcode Fetch)
0	X	1	DMA Operation
0	0	0	HALT Mode
1	0	1	SLEEP Mode (Including SYSTEM STOP Mode)

Notes:
X = Do not care.
MC = Machine Cycle.

$\overline{TEND0}$, $\overline{TEND1}$. Transfer End 0 and 1 (Outputs, active Low). This output is asserted active during the most recent WRITE cycle of a DMA operation. It is used to indicate the end of the block transfer. $\overline{TEND0}$ is multiplexed with CKA1.

TEST. Test (Output, not in DIP version). This pin is for test and should be left open.

T_{OUT}. Timer Out (Output). T_{OUT} is the output from PRT channel 1. This line is multiplexed with A18 of the address bus.

TXA0, TXA1. Transmit Data 0 and 1 (Outputs). These signals are the transmitted data from the ASCI channels. Transmitted data changes are with respect to the falling edge of the transmit clock.

TXS. Clocked Serial Transmit Data (Output). This line is the transmitted data from the CSI/O channel.

$\overline{WAIT}$. Wait (Input, active Low). $\overline{WAIT}$ indicates to the MPU that the addressed memory or I/O devices are not ready for data transfer. This input is sampled on the falling edge of T2 (and subsequent WAIT states). If the input is sampled Low, then the additional WAIT states are inserted until the $\overline{WAIT}$ input is sampled High, at which time execution continues.

$\overline{WR}$. WRITE (Output, active Low, 3-state). $\overline{WR}$ indicates that the CPU data bus holds valid data to be stored at the addressed I/O or memory location.

XTAL. Crystal Oscillator Connection (Input). This pin should be left open if an external clock is used instead of a crystal. The oscillator input is not a TTL level (see DC Characteristics).

Several pins are used for different conditions, depending on the circumstance.

ARCHITECTURE

The Z180 combines a high-performance CPU core with a variety of system and I/O resources useful in a broad range of applications. The CPU core consists of five functional blocks: clock generator, bus state controller, Interrupt controller, memory management unit (MMU), and the central processing unit (CPU). The integrated I/O resources make up the remaining four functional blocks: direct memory access (DMA) control (2 channels), asynchronous serial communication interface (ASCI, 2 channels) programmable reload timers (PRT, 2 channels), and a clock serial I/O (CSI/O) channel.

Clock Generator. This logic generates a system clock from an external crystal or clock input. The external clock is divided by 2 or 1 and provides the timing for both internal and external devices.

Bus State Controller. This logic performs all of the status and bus-control activity associated with the CPU and some on-chip peripherals. Also includes wait-state timing, reset cycles, DRAM refresh, and DMA bus exchanges.

Interrupt Controller. This logic monitors and prioritizes the variety of internal and external interrupts and traps to provide the correct responses from the CPU. To maintain compatibility with the Z80 CPU, three different interrupts modes are supported.

Memory Management Unit. The MMU allows the user to map the memory used by the CPU (logically only 64KB) into the 1-MB addressing range supported by the Z8S180/Z8L180. The organization of the MMU object code maintains compatibility with the Z80 CPU, while offering access to an extended memory space. Accomplished by using an effective common-area/banked-area scheme.

Central Processing Unit. The CPU is microcoded to provide a core that is object-code compatible with the Z80 CPU. It also provides a superset of the Z80 instruction set, including 8-bit multiplication. The core is modified to allow many of the instructions to execute in fewer clock cycles.

DMA Controller. The DMA controller provides high-speed transfers between memory and I/O devices. Transfer operations supported are memory-to-memory, memory to/from I/O, and I/O-to-I/O. Transfer modes supported are request, burst, and cycle steal. DMA transfers can access the full 1-MB address range with a block length up to 64 KB, and can cross over 64K boundaries.

Asynchronous Serial Communication Interface (ASCI).

The ASCI logic provides two individual full-duplex UARTs. Each channel includes a programmable baud rate generator and modem control signals. The ASCI channels can also support a multiprocessor communication format as well as break detection and generation

Programmable Reload Timers (PRT). This logic consists of two separate channels, each containing a 16-bit counter (timer) and count reload register. The time base for the counters is derived from the system clock (divided by 20) before reaching the counter. PRT channel 1 provides an optional output to allow for waveform generation.

OPERATION MODES (Continued)

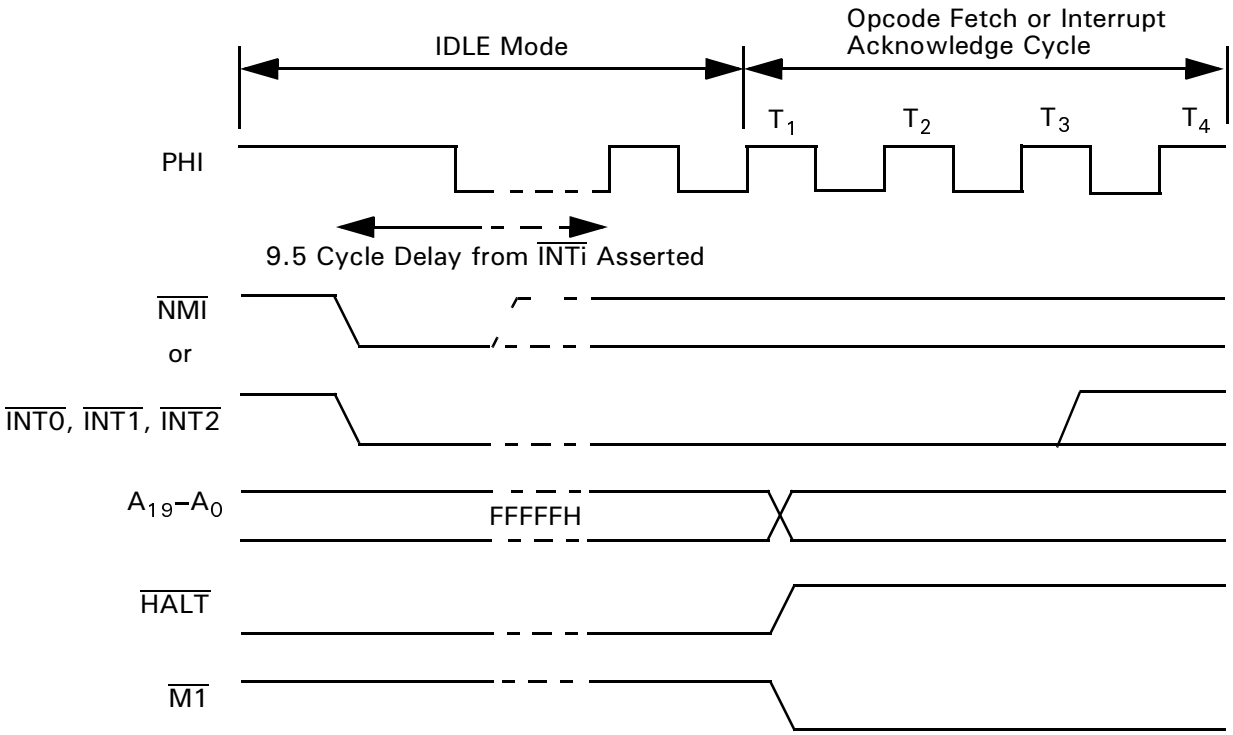


Figure 15. Z8S180/Z8L180 IDLE Mode Exit Due To External Interrupt

While the Z8S180/Z8L180 is in IDLE mode, it grants the bus to an external Master if the BREXT bit (CCR5) is 1. Figure 16 depicts the timing for this sequence.

Note: A response to a bus request takes 8 clock cycles longer than in normal operation.

After the external Master negates the Bus Request, the Z8S180/Z8L180 disables the PHI clock and remains in IDLE mode.

Table 7. Z8L180 DC Characteristics
V_{DD} = 3.3V ±10%; V_{SS} = 0V

Symbol	Item	Condition	Min	Typ	Max	Unit
V_{IH1}	Input H Voltage $\overline{RESET}$, EXTAL, $\overline{NMI}$		V_{DD} –0.6		V_{DD} +0.3	V
V_{IH2}	Input H Voltage Except $\overline{RESET}$, EXTAL, $\overline{NMI}$		2.0		V_{DD} +0.3	V
V_{IL1}	Input L Voltage RESET, EXTAL, NMI		–0.3		0.6	V
V_{IL2}	Input L Voltage Except RESET, EXTAL, NMI		–0.3		0.8	V
V_{OH}	Outputs H Voltage All outputs	I_{OH} = –200 µA	2.15			V
		I_{OH} = –20 µA	V_{DD} –0.6			V
V_{OL}	Outputs L Voltage All Outputs	I_{OL} = 4 mA			0.4	V
I_{IL}	Input Leakage Current All Inputs Except XTAL, EXTAL	V_{IN} = 0.5 ~ V_{DD} –0.5			1.0	µA
I_{TL}	Three State Leakage Current	V_{IN} = 0.5 ~ V_{DD} –0.5			1.0	µA
I_{DD1}	Power Dissipation (Normal Operation)	F = 20 MHz		30	60	mA
		4 MHz		4	10	
	Power Dissipation (SYSTEM STOP mode)	F = 20 MHz		5	10	
		4 MHz		2	5	
C_P	Pin Capacitance	V_{IN} = 0V, f = 1 MHz T_A = 25° C			12	pF

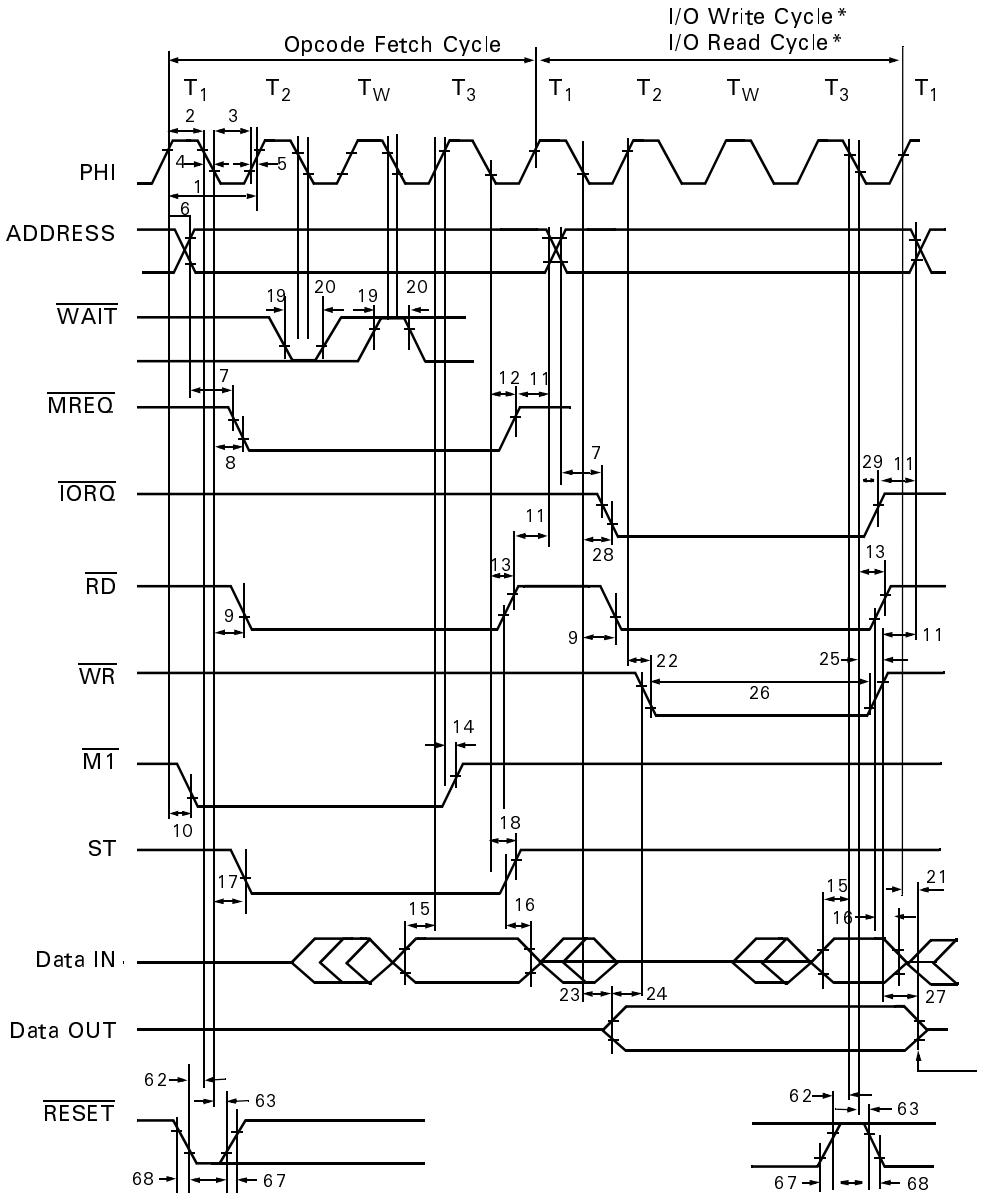
Note:
1. V_{IHmin} = V_{DD} –1.0V, V_{ILmax} = 0.6V (All output terminals are at NO LOAD.) V_{DD} = 3.0V.

AC CHARACTERISTICS—Z8S180 (Continued)

Table 8. Z8S180 AC Characteristics (Continued)
V_{DD} = 5V ±10% or V_{DD} = 3.3V ±10%; 33-MHz Characteristics Apply Only to 5V Operation

			Z8S180—20 MHz		Z8S180—33 MHz		
Number	**Symbol**	**Item**	**Min**	**Max**	**Min**	**Max**	**Unit**
32	t_{INTH}	$\overline{INT}$ Hold Time from PHI Fall	10	—	10	—	ns
33	t_{NMIW}	$\overline{NMI}$ Pulse Width	35	—	25	—	ns
34	t_{BRS}	$\overline{BUSREQ}$ Set-up Time to PHI Fall	10	—	10	—	ns
35	t_{BRH}	$\overline{BUSREQ}$ Hold Time from PHI Fall	10	—	10		ns
36	t_{BAD1}	PHI Rise to $\overline{BUSACK}$ Fall Delay	—	25	—	15	ns
37	t_{BAD2}	PHI Fall to $\overline{BUSACK}$ Rise Delay	—	25	—	15	ns
38	t_{BZD}	PHI Rise to Bus Floating Delay Time	—	40	—	30	ns
39	t_{MEWH}	$\overline{MREQ}$ Pulse Width (High)	35	—	25	—	ns
40	t_{MEWL}	$\overline{MREQ}$ Pulse Width (Low)	35	—	25	—	ns
41	t_{RFD1}	PHI Rise to $\overline{RFSH}$ Fall Delay	—	20	—	15	ns
42	t_{RFD2}	PHI Rise to $\overline{RFSH}$ Rise Delay	—	20	—	15	ns
43	t_{HAD1}	PHI Rise to $\overline{HALT}$ Fall Delay	—	15	—	15	ns
44	t_{HAD2}	PHI Rise to $\overline{HALT}$ Rise Delay	—	15	—	15	ns
45	t_{DRQS}	$\overline{DREQ1}$ Set-up Time to PHI Rise	20	—	15	—	ns
46	t_{DRQH}	$\overline{DREQ1}$ Hold Time from PHI Rise	20	—	15	—	ns
47	t_{TED1}	PHI Fall to $\overline{TENDi}$ Fall Delay	—	25	—	15	ns
48	t_{TED2}	PHI Fall to $\overline{TENDi}$ Rise Delay	—	25	—	15	ns
49	t_{ED1}	PHI Rise to E Rise Delay	—	30	—	15	ns
50	t_{ED2}	PHI Fall or Rise to E Fall Delay	—	30	—	15	ns
51	P_{WEH}	E Pulse Width (High)	25	—	20	—	ns
52	P_{WEL}	E Pulse Width (Low)	50	—	40	—	ns
53	t_{Er}	Enable Rise Time	—	10	—	10	ns
54	t_{Ef}	Enable Fall Time	—	10	—	10	ns
55	t_{TOD}	PHI Fall to Timer Output Delay	—	75	—	50	ns
56	t_{STDI}	CSI/O Transmit Data Delay Time (Internal Clock Operation)	—	2	—	2	tcyc
57	t_{STDE}	CSI/O Transmit Data Delay Time (External Clock Operation)	—	7.5 t_{CYC} +75	—	75 t_{CYC} +60	ns
58	t_{SRSI}	CSI/O Receive Data Set-up Time (Internal Clock Operation)	1	—	1	—	tcyc
59	t_{SRHI}	CSI/O Receive Data Hold Time (Internal Clock Operation)	1	—	1	—	tcyc
60	t_{SRSE}	CSI/O Receive Data Set-up Time (External Clock Operation)	1	—	1	—	tcyc
61	t_{SRHE}	CSI/O Receive Data Hold Time (External Clock Operation)	1	—	1	—	tcyc
62	t_{RES}	$\overline{RESET}$ Set-up Time to PHI Fall	40	—	25	—	ns

TIMING DIAGRAMS



Note: *Memory Read/Write Cycle timing is the same as I/O Read/Write Cycle except there are no automatic wait states (T_W), and $\overline{MREQ}$ is active instead of $\overline{IORQ}$.

Figure 20. CPU Timing
(Opcode Fetch Cycle, Memory Read Cycle, Memory Write Cycle, I/O Write Cycle, I/O Read Cycle)

TIMING DIAGRAMS (Continued)

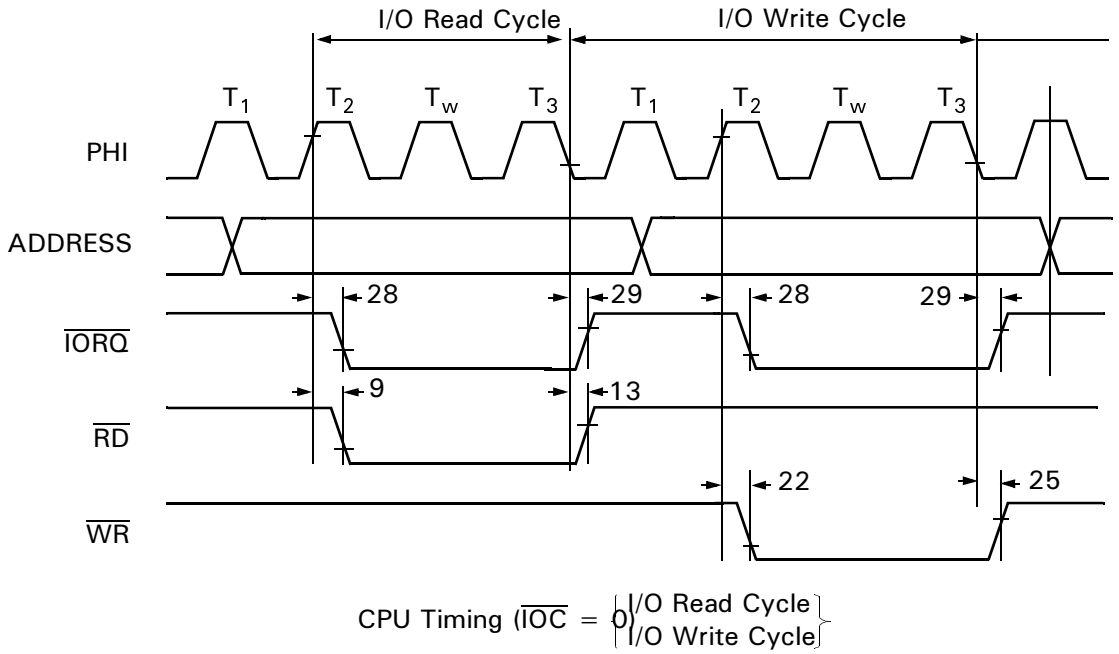
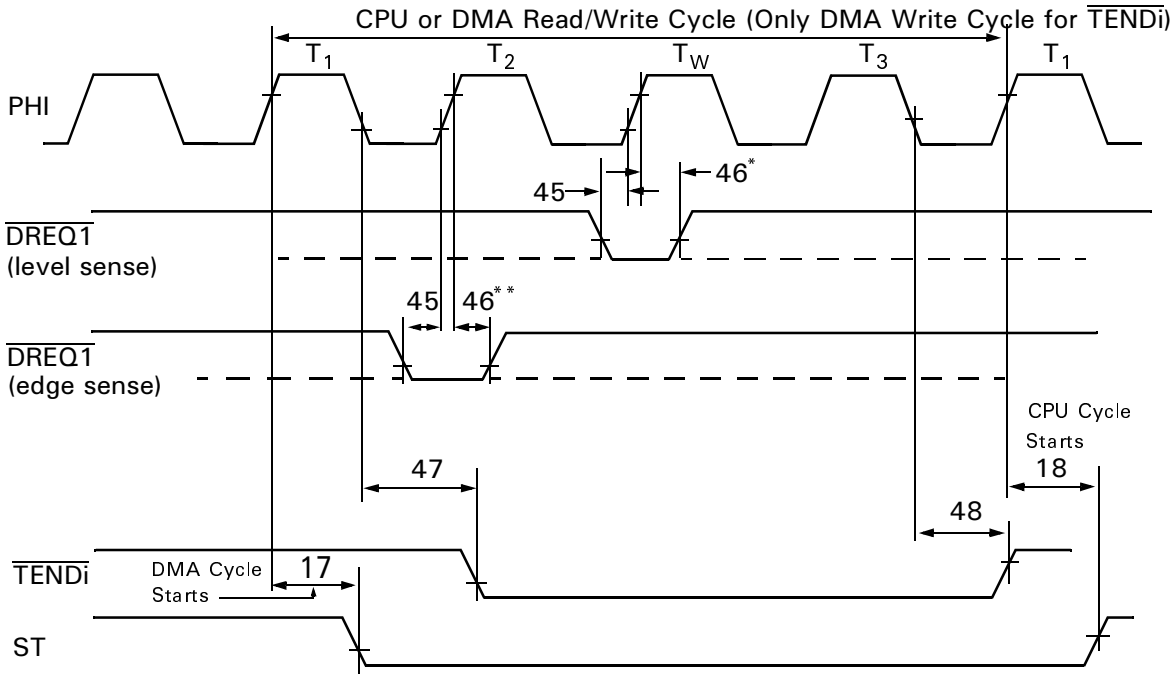


Figure 22. CPU Timing ($\overline{IOC}$ = 0) (I/O Read Cycle, I/O Write Cycle)



Notes:

*T_{DRQS} and T_{DRQH} are specified for the rising edge of the clock followed by T_3.

**T_{DRQS} and T_{DRQH} are specified for the rising edge of the clock.

Figure 23. DMA Control Signals

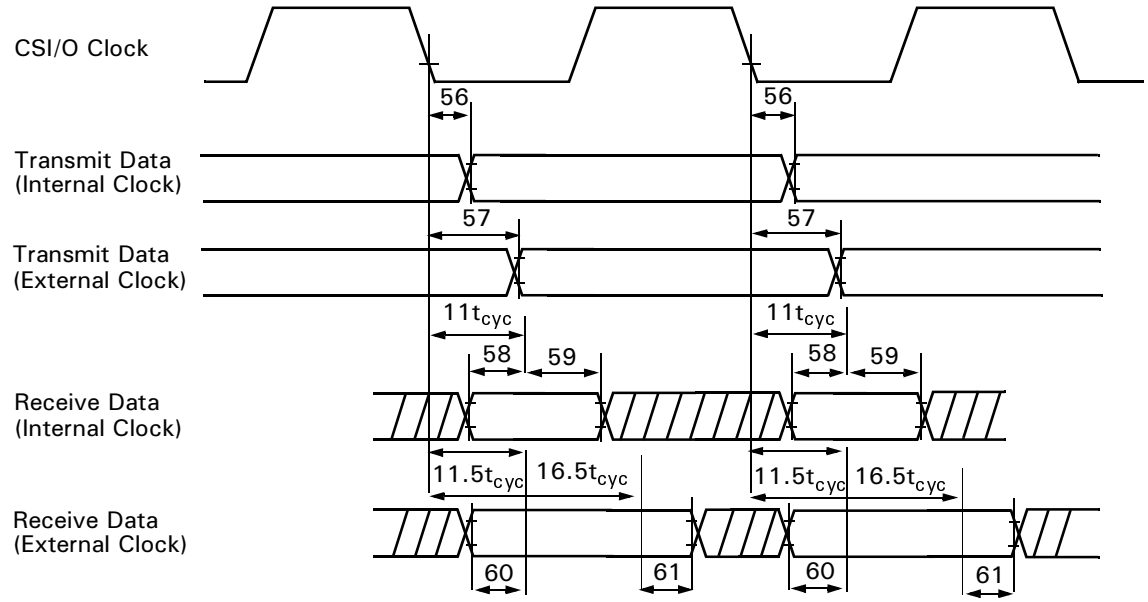


Figure 29. CSI/O Receive/Transmit Timing

External Clock Rise Time and Fall Time

Input Rise Time and Fall Time (Except EXTAL, $\overline{\text{RESET}}$)

Figure 30. Rise Time and Fall Times

ASCI STATUS REGISTER 0,1

Each ASCI channel status register (STAT0,1) allows interrogation of ASCI communication, error and modem control signal status, and the enabling or disabling of ASCI interrupts.

ASCI Status Register 0 (STAT0: I/O Address = 04H)

Bit	7	6	5	4	3	2	1	0
	RDRF	OVRN	PE	FE	RE	$\overline{DCD0}$	TDRE	TIE
	R	R	R	R	R/W	R	R	R/W

ASCI Status Register 1 (STAT1: I/O Address = 05H)

Bit	7	6	5	4	3	2	1	0
	RDRF	OVRN	PE	FE	RE	CTS1E	TDRE	TIE
	R	R	R	R	R/W	R/W	R	R/W

Figure 35. ASCI Status Registers

RDRF: Receive Data Register Full (Bit 7). RDRF is set to 1 when an incoming data byte is loaded into an empty Rx FIFO. If a framing or parity error occurs, RDRF is still set and the receive data (which generated the error) is still loaded into the FIFO. RDRF is cleared to 0 by reading RDR and most recently received character in the FIFO from IOSTOP mode, during RESET and for ASCI0 if the $\overline{DCD0}$ input is auto-enabled and is negated (High).

OVRN: Overrun Error (Bit 6). An overrun condition occurs if the receiver finishes assembling a character but the Rx FIFO is full so there is no room for the character. However, this status bit is not set until the most recent character received before the overrun becomes the oldest byte in the FIFO. This bit is cleared when software writes a 1 to the EFR bit in the CNTLA register. The bit may also be cleared by RESET in IOSTOP mode or ASCI0 if the $\overline{DCD0}$ pin is auto enabled and is negated (High).

Note: When an overrun occurs, the receiver does not place the character in the shift register into the FIFO, nor any subsequent characters, until the most recent good character enters the top of the FIFO so that OVRN is set. Software then writes a 1 to EFR to clear it.

PE: Parity Error (Bit 5). A parity error is detected when parity checking is enabled.When the MOD1 bit in the CNTLA register is 1, a character is assembled in which the parity does not match the PEO bit in the CNTLB register. However, this status bit is not set until or unless the error character becomes the oldest one in the Rx FIFO. PE is cleared when software writes a 1 to the EFR bit in the CNTRLA register. PE is also cleared by RESET in IOSTOP mode, or on ASCI0, if the $\overline{DCD0}$ pin is auto-enabled and is negated (High).

FE: Framing Error (Bit 4). A framing error is detected when the stop bit of a character is sampled as 0/SPACE. However, this status bit is not set until/unless the error character becomes the oldest one in the Rx FIFO. FE is cleared when software writes a 1 to the EFR bit in the CNTLA register. FE is also cleared by RESET in IOSTOP mode, or on ASCI0, if the $\overline{DCD0}$ pin is auto-enabled and is negated (High).

REI: Receive Interrupt Enable (Bit 3). RIE should be set to 1 to enable ASCI receive interrupt requests. When RIE is 1, the Receiver requests an interrupt when a character is received and RDRF is set, but only if neither DMA channel requires its request-routing field to be set to receive data from this ASCI. That is, if SM1–0 are 11 and SAR17–16 are 10, or DIM1 is 1 and IAR17–16 are 10, then ASCI1 does not request an interrupt for RDRF. If RIE is 1, either ASCI requests an interrupt when OVRN, PE or FE is set, and

never both set to 1 at the same time. TE is cleared to 0 during RESET and IOSTOP mode.

SS2, 1, 0: Speed Select 2, 1, 0 (Bits 2–0). SS2, SS1 and SS0 select the CSI/O transmit/receive clock source and speed. SS2, SS1 and SS0 are all set to 1 during $\overline{\text{RESET}}$. Table 11 indicates CSI/O Baud Rate Selection.

Table 11. CSI/O Baud Rate Selection

SS2	SS1	SS0	Divide Ratio
0	0	0	÷20
0	0	1	÷40
0	1	0	÷80
0	1	1	÷160
1	0	0	÷320
1	0	1	÷640
1	1	0	÷1280
1	1	1	External Clock Input (Less Than ÷20)

After $\overline{\text{RESET}}$, the CKS pin is configured as an external clock input (SS2, SS1, SS0 = 1). Changing these values causes CKS to become an output pin and the selected clock is output when transmit or receive operations are enabled.

CSI/O Transmit/Receive Data Register

Mnemonic TRDR
Address 0BH

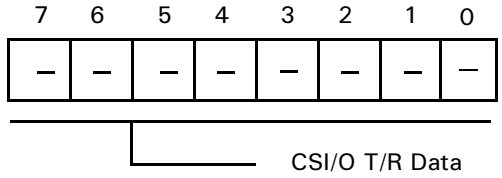


Figure 41. CSI/O Transmit/Receive Data Register

Timer Data Register Channel 0 Low

Mnemonic TMDR0L
Address 0CH

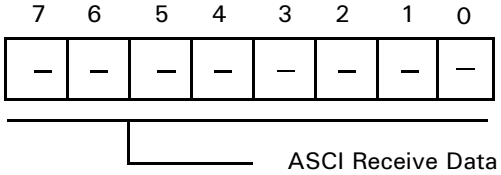


Figure 42. Timer Register Channel 0 Low

Timer Data Register Channel 0H

Mnemonic TMDR0H
Address 0DH

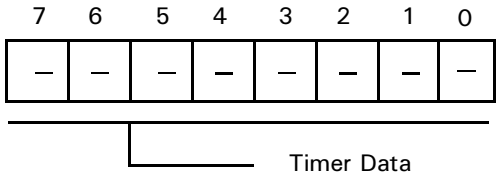


Figure 43. Timer Data Register Channel 0 High

Timer Reload Register Channel 0 Low

Mnemonic RLDR0L
Address 0EH

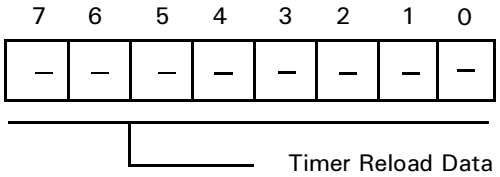


Figure 44. Timer Reload Register Low

Timer Reload Register Channel 0 High

Mnemonic RLDR0H
Address 0FH

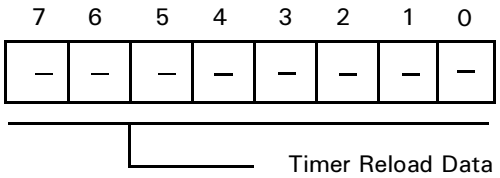


Figure 45. Timer Reload Register Channel 0 High

TIMER CONTROL REGISTER

The Timer Control Register (TCR) monitors both channels (PRT0, PRT1) TMDR status. It also controls the enabling and disabling of down-counting and interrupts, and controls the output pin A18/T_{OUT} for PRT1.

Bit	7	6	5	4	3	2	1	0
	TIF1	TIF0	TIE1	TIE0	TOC1	TOC0	TDE1	TDE0
	R	R	R/W	R/W	R/W	R/W	R/W	R/W

Figure 46. Timer Control Register (TCR: I/O Address = 10H)

TIF1: Timer Interrupt Flag 1 (Bit 7) . When TMDR1 decrements to 0, TIF1 is set to 1. This condition generates an interrupt request if enabled by TIE1 = 1. TIF1 is reset to 0 when TCR is read and the higher or lower byte of TMDR1 is read. During RESET, TIF1 is cleared to 0.

TIF0: Timer Interrupt Flag 0 (Bit 6). When TMDR0 decrements to 0, TIF0 is set to 1. This condition generates an interrupt request if enabled by TIE0 = 1. TIF0 is reset to 0 when TCR is read and the higher or lower byte of TMDR0 is read. During RESET, TIF0 is cleared to 0.

TIE1: Timer Interrupt Enable 1 (Bit 5). When TIE0 is set to 1, TIF1 = 1 generates a CPU interrupt request. When TIE0 is reset to 0, the interrupt request is inhibited. During RESET, TIE0 is cleared to 0.

TOC1, 0: Timer Output Control (Bits 3, 2). TOC1 and TOC0 control the output of PRT1 using the multiplexed A18/T_{OUT} pin as indicated in Table 12. During RESET, TOC1 and TOC0 are cleared to 0. If bit 3 of the IAR1B register is 1, the T_{OUT} function is selected. By programming TOC1 and TOC0, the A18/T_{OUT} pin can be forced High, Low, or toggled when TMDR1 decrements to 0.

Table 12. Timer Output Control

TOC1	TOC0	Output	
0	0	Inhibited	The A18/T_{OUT} pin is not affected by the PRT
0	1	Toggled	If bit 3 of IAR1B is 1, the A18/T_{OUT} pin is toggled or set Low or High as indicated
1	0	0	
1	1	1	

TDE1, 0: Timer Down Count Enable (Bits 1, 0). TDE1 and TDE0 enable and disable down-counting for TMDR1 and TMDR0, respectively. When TDEn (n = 0,1) is set to 1, down-counting is stopped and TMDRn is freely read or written. TDE1 and TDE0 are cleared to 0 during RESET and TMDRn does not decrement until TDEn is set to 1.

ASCI EXTENSION CONTROL REGISTER CHANNEL 0 AND CHANNEL 1 (Continued)

Timer Data Register Channel 1 Low

Mnemonic TMDR1L
Address 14H

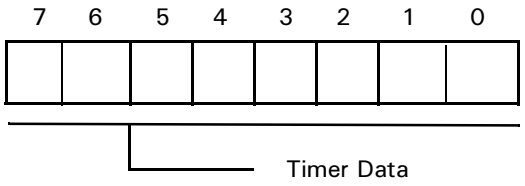


Figure 48. Timer Data Register 1 Low

Timer Data Register Channel 1 High

Mnemonic TMDR1H
Address 15H

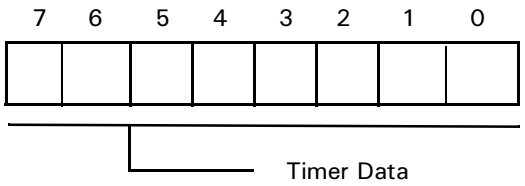


Figure 49. Timer Data Register 1 High

Timer Reload Register Channel 1 Low

Mnemonic RLDR1L
Address 16

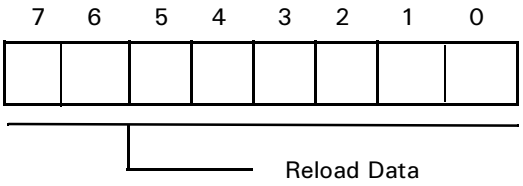


Figure 50. Timer Reload Channel 1 Low

Timer Reload Register Channel 1 High

Mnemonic RLDR1H
Address 17H

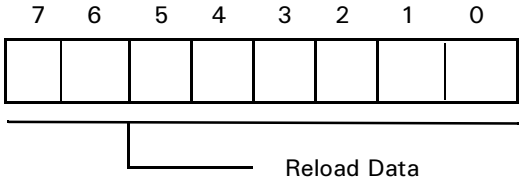


Figure 51. Timer Reload Register Channel 1 High

Free Running Counter (Read Only)

Mnemonic FRC
Address 18H

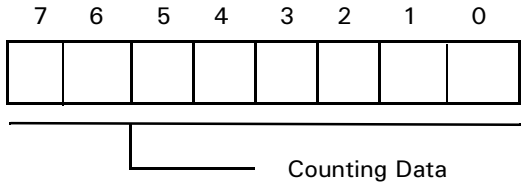


Figure 52. Free Running Counter

ASCI TIME CONSTANT REGISTERS

If the SS2–0 bits of the CNTLB register are not 111, and the BRG mode bit in the ASEXT register is 1, the ASCI divides the PHI clock by two times the registers' 16-bit value, plus two. As a result, the clock is presented to the transmitter and receiver for division by 1, 16, or 64, and is output on the CKA pin.

If the SS2–0 bits in an ASCI CNTLB register are not 111, and the BRG mode bit in its Extension Control Register is 1, its *new* baud rate generator divides PHI for serial clocking, as follows:

$$\text{bits/second} = f_{PHI}/(2*(TC+2) \times \text{sampling rate})$$

where TC is the 16-bit value programmed into the ASCI Time Constant High and Low registers. If the ASCI multiplexed CKA pin is selected for the CKA function, it outputs the clock before the final division by the sampling rate, as follows:

$$f_{CKAout} = f_{PHI}/(2*(TC+2))$$

Find the TC value for a particular serial bit rate as follows:

$$TC = (f_{PHI}/(2 \times \text{bits/second} \times \text{sampling rate})) - 2$$

ASCI Time Constant Register 0 Low (ASTC0L, I/O Address 1AH)
ASCI Time Constant Register 1 Low (ASTC1L, I/O Address 1CH)

Bit	7	6	5	4	3	2	1	0
	LS 8 Bits of Time Constant							

ASCI Time Constant Register 0 High (ASTC0H, I/O Address 1BH)
ASCI Time Constant Register 1 High (ASTC1H, I/O Address 1DH)

Bit	7	6	5	4	3	2	1	0
	MS 8 Bits of Time Constant							

Figure 53. ASCI Time Constant Registers

DMA SOURCE ADDRESS REGISTER CHANNEL 0

The DMA Source Address Register Channel 0 specifies the physical source address for channel 0 transfers. The register contains 20 bits and can specify up to 1024 KB memory addresses or up to 64-KB I/O addresses. Channel 0 source can be memory, I/O, or memory mapped I/O. For I/O, bits 17–16 of this register identify the Request Handshake signal.

DMA Source Address Register, Channel 0 Low

Mnemonic SAR0L
Address 20H

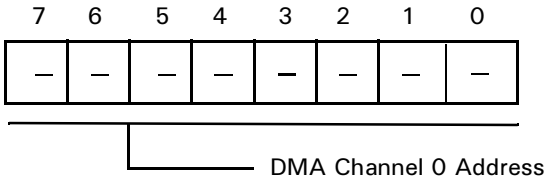


Figure 55. DMA Source Address Register 0 Low

DMA Source Address Register, Channel 0 High

Mnemonic SAR0H
Address 21H

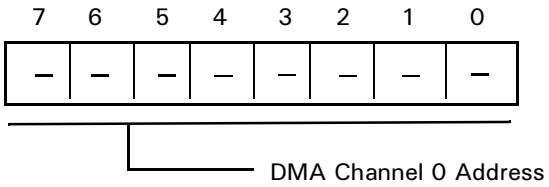


Figure 56. DMA Source Address Register 0 High

DMA Source Address Register Channel 0B

Mnemonic SAR0B
Address 22H

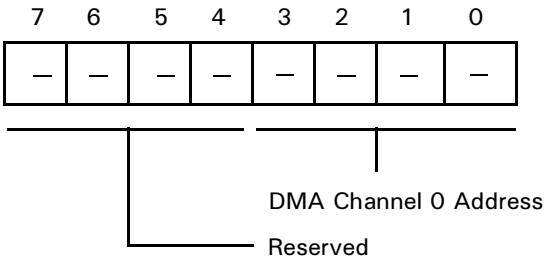


Figure 57. DMA Source Address Register 0B

If the source is in I/O space, bits 1–0 of this register select the DMA request signal for DMA0, as follows:

Bit 1 (A17)	Bit 0 (A16)	DMA Transfer Request
0	0	DREQ0 (external)
0	1	RDRF (ASCI0)
1	0	RDRF (ASCI1)
1	1	Reserved

DMA/WAIT CONTROL REGISTER

The DMA/WAIT Control Register (DCNTL) controls the insertion of wait states into DMAC (and CPU) accesses of memory or I/O. Also, the register defines the Request signal for each channel as level or edge sense. DCNTL also sets the DMA transfer mode for channel 1, which is limited to memory to/from I/O transfers.

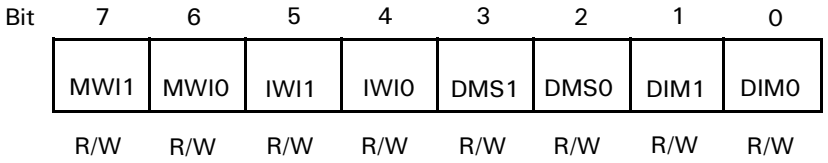


Figure 73. DMA/WAIT Control Register (DCNTL: I/O Address = 32H)

MWI1, MWI0: Memory Wait Insertion (Bits 7–6). This bit specifies the number of wait states introduced into CPU or DMAC memory access cycles. MWI1 and MWI0 are set to 1 during RESET.

MWI1	MWI0	Wait State
0	0	0
0	1	1
1	0	2
1	1	3

IWI1, IWI0: I/O Wait Insertion (Bits 5–4). This bit specifies the number of wait states introduced into CPU or DMAC I/O access cycles. IWI1 and IWI0 are set to 1 during RESET.

IWI1	IWI0	Wait State
0	0	1
0	1	2
1	0	3
1	1	4

Note: These wait states are added to the 3-clock I/O cycle that is used to access the on-chip I/O registers. It is equally valid to regard these as 0 to 3 wait states added to a 4-clock external I/O cycle.

DMS1, DMS0: DMA Request Sense (Bits 3–2). DMS1 and DMS0 specify the DMA request sense for channel 0 and channel 1 respectively. When reset to 0, the input is level sense. When set to 1, the input is edge sense. DMS1 and DMS0 are cleared to 0 during RESET.

DMSi	Sense
1	Edge Sense
0	Level Sense

Typically, for an input/source device, the associated DMS bit should be programmed as 0 for level sense. The device takes a relatively long time to update its Request signal after the DMA channel reads data (in the first of the two machine cycles involved in transferring a byte).

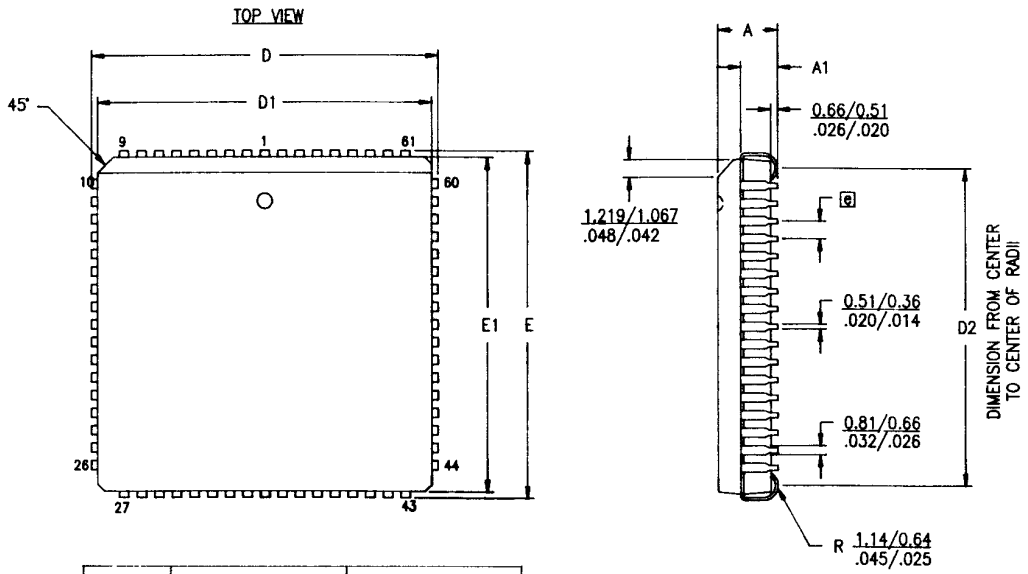
An output/destination device takes much less time to update its Request signal after the DMA channel starts a WRITE operation to it (the second machine cycle of the two cycles involved in transferring a byte). With zero-wait state I/O cycles, a device cannot update its request signal in the required time, so edge sensing must be used.

A one-wait-state I/O cycle also does not provide sufficient time for updating, so edge sensing is again required.

DIM1, DIM0: DMA Channel 1 I/O and Memory Mode (Bits 1–0). Specifies the source/destination and address modifier for channel 1 memory to/from I/O transfer modes. DIM1 and DIM0 are cleared to 0 during RESET.

Table 17. Channel 1 Transfer Mode

DIM1	DMI0	Transfer Mode	Address Increment/Decrement
0	0	Memory→I/O	MAR1 +1, IAR1 fixed
0	1	Memory→I/O	MAR1 –1, IAR1 fixed
1	0	I/O→Memory	IAR1 fixed, MAR1 +1
1	1	I/O→Memory	IAR1 fixed, MAR1 –1



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	4.32	4.57	.170	.180
A1	2.43	2.92	.095	.115
D/E	25.02	25.40	.985	1.000
D1/E1	24.13	24.33	.950	.958
D2	22.86	23.62	.900	.930
e	1.27 TYP		.050 TYP	

NOTES:
1. CONTROLLING DIMENSIONS : INCH
2. LEADS ARE COPLANAR WITHIN .004 IN RANGE.
3. DIMENSION : MM / INCH

Figure 87. 68-Pin PLCC Package Diagram

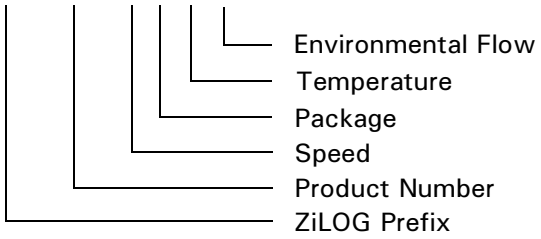
ORDERING INFORMATION

Codes	
Speed	10 = 10 MHz
	20 = 20 MHz
	33 = 33 MHz
Package	P = 60-Pin Plastic DIP
	V = 68-Pin PLCC
	F = 80-Pin QFP
Temperature	S = 0°C to +70°C
	E = –40°C to +85°C
Environmental	C = Plastic Standard

For fast results, contact your local ZiLOG sales office for assistance in ordering the part(s) required.

Example:

Z 8S180 10 P S C is a Z8S180 10-MHz 60-Pin DIP, 0° to +70°C, Plastic Standard Flow



Pre-Characterization Product

The product represented by this document is newly introduced and ZiLOG has not completed the full characterization of the product. The document states what ZiLOG knows about this product at this time, but additional features or non-conformance with some aspects of the document may be found, either by ZiLOG or its customers in the course of further application and characterization work. In addition, ZiLOG cautions that delivery may be uncertain at times, due to start-up yield issues.

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